

# SI2310A

N-Channel MOSFET

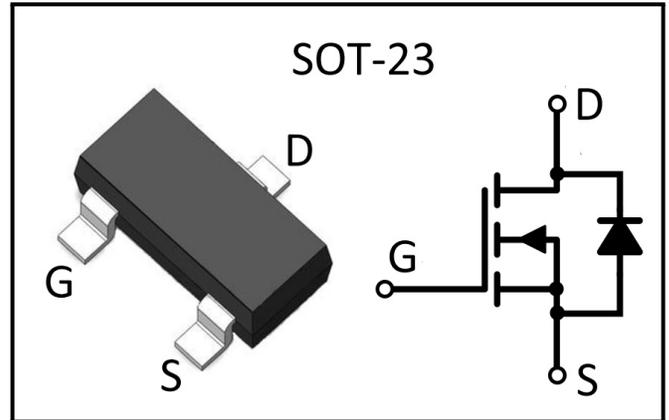
## Features

- $V_{DS(V)}=60V$
- $I_D=3A$
- $R_{DS(ON)}@V_{GS(V)}=10V,TYP=80m\Omega$
- $R_{DS(ON)}@V_{GS(V)}=4.5V,TYP=90m\Omega$

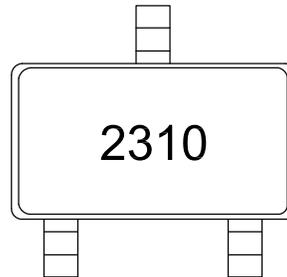
## General Description

- Advanced trench process technology
- High Density Cell Design For Ultra Low On-Resistance
- SOT-23 for Surface Mount Package.

## Package



## Marking



## Ordering information

Order code	Package	Marking	Base qty	Delivery mode
SI2310A	SOT-23	2310	3K	Tape and reel

## Absolute Maximum Ratings (@ $T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	3	A
$I_{DM}$	Pulsed drain current	10	A
$P_D$	Power dissipation	350	mW
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	357	$^\circ C/W$
$T_J$	Operating Junction Temperature	150	$^\circ C$
$T_{stg}$	Storage Temperature Range	-55 to +150	$^\circ C$



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**Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise noted**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250uA	60	–	–	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	–	–	1	uA
I <sub>GSS</sub>	Gate Body Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	–	–	±0.1	uA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	0.8	1.5	2	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance <sup>(1)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3A	–	80	105	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A	–	90	125	
<b>Dynamic Characteristics<sup>(2)</sup></b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, f=1MHz	–	247	–	pF
C <sub>oss</sub>	Output Capacitance		–	34	–	
C <sub>rss</sub>	Reverse Transfer Capacitance		–	22	–	
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =30V, I <sub>D</sub> =1.5A, V <sub>GEN</sub> =10V, R <sub>GEN</sub> =1Ω	–	6	–	nS
t <sub>r</sub>	Turn-On Rise Time		–	15	–	
t <sub>d(off)</sub>	Turn-Off Delay Time		–	15	–	
t <sub>f</sub>	Turn-Off Fall Time		–	10	–	
Q <sub>g</sub>	Total gate charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =30V, I <sub>D</sub> =3A	–	5.1	–	nC
Q <sub>gs</sub>	Gate-source charge		–	1.3	–	
Q <sub>gd</sub>	Gate-drain charge		–	1.7	–	
<b>Source-Drain Diode Characteristics</b>						
I <sub>S</sub>	Diode forward Current <sup>(1)</sup>	–	–	–	3	A
V <sub>DS</sub>	Diode forward voltage	V <sub>GS</sub> =0V, I <sub>S</sub> = 3A	–	0.85	1.25	V

Notes:

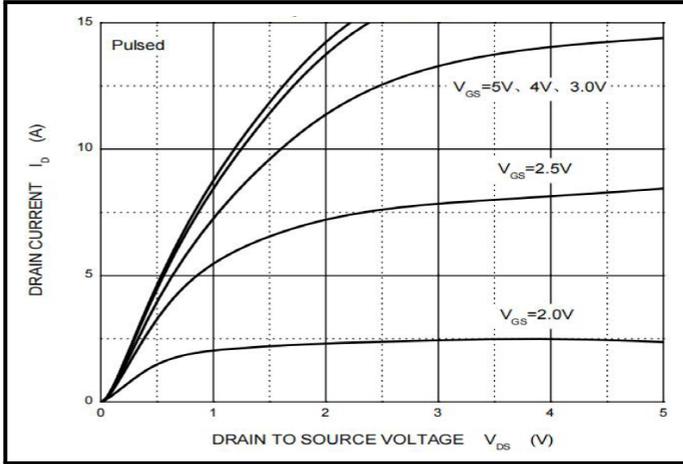
(1)Pulse test: Pulse width ≤300 μs, duty cycle ≤2%.

(2)Guaranteed by design, not subject to production testing.

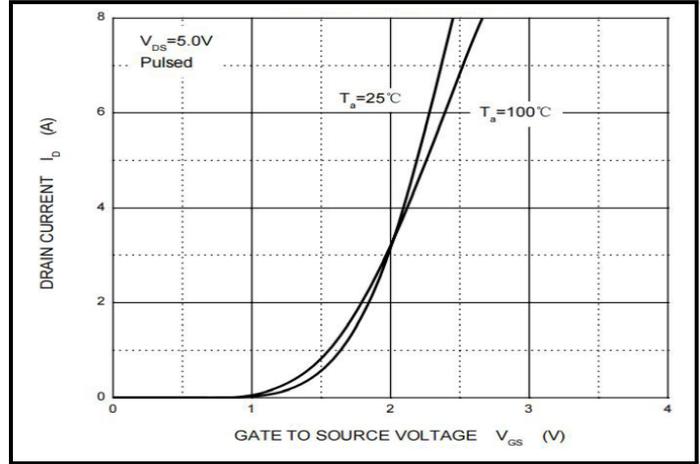


Typical Performance Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)

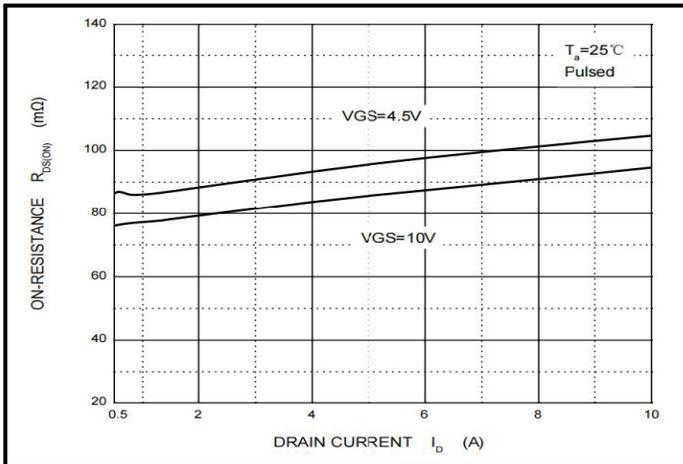
**Figure 1 :Output Characteristics**



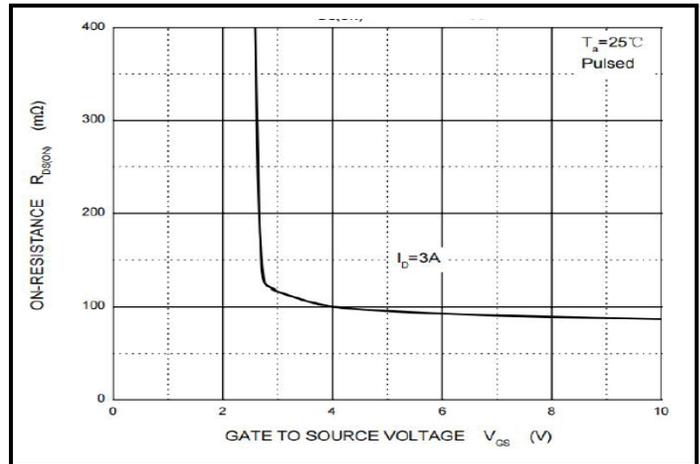
**Figure 2 :Transfer Characteristics**



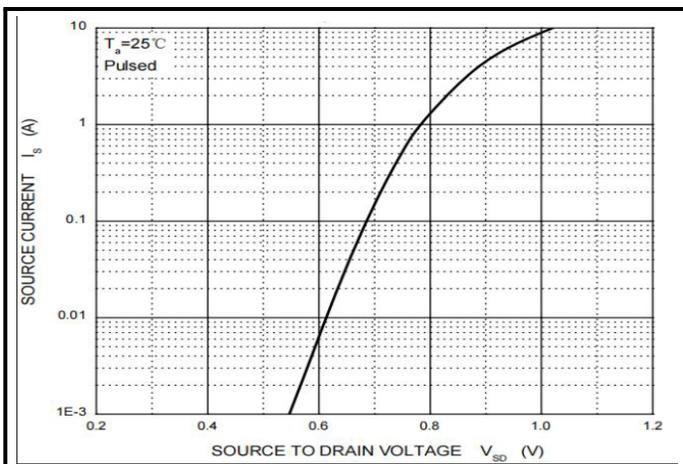
**Figure 3 : $R_{DS(on)}$ — $I_D$**



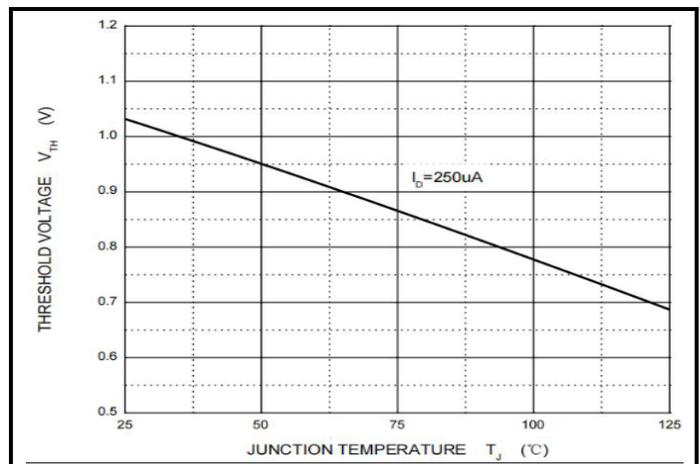
**Figure 4 : $R_{DS(on)}$ — $V_{GS}$**



**Figure 5 : $I_S$ — $V_{SD}$**



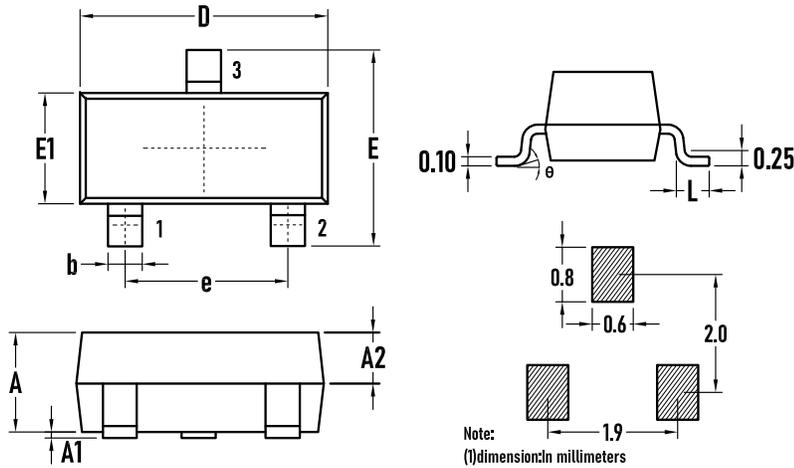
**Figure 6 :Threshold Voltage**



**SI2310A**

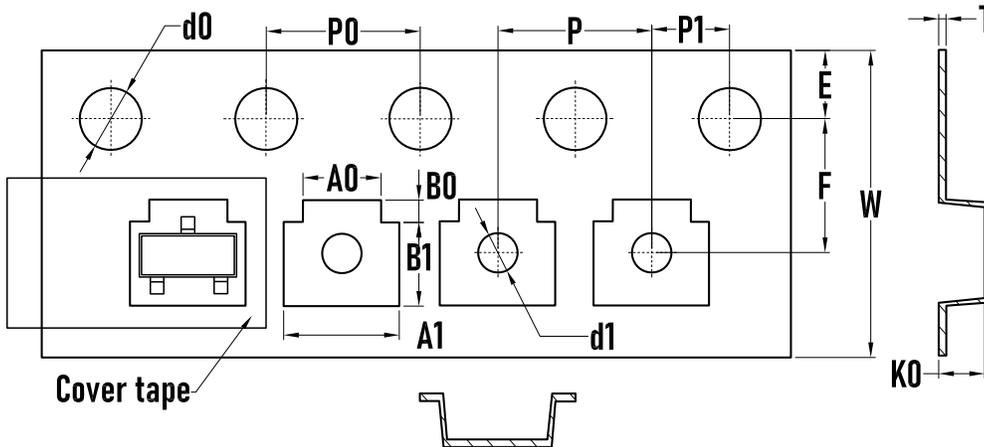
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**Outline Drawing - SOT-23**



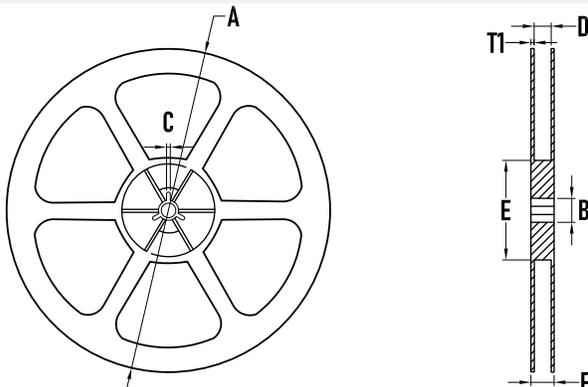
SYMBOL	MILLIMETER		
	MIN.	Typ.	MAX.
A	0.90	1.00	1.10
A1	0.01	–	0.10
A2	0.50	0.60	0.70
D	2.80	2.90	3.00
b	0.25	0.35	0.45
E	2.10	2.30	2.50
E1	1.20	1.30	1.40
e	1.80	1.90	2.00
L	0.25	0.35	0.45
θ	0	–	8°

**Packaging Tape - SOT-23**



SYMBOL	MILLIMETER
A0	2.10±0.10
A1	3.10±0.10
B0	0.65±0.10
B1	2.75±0.10
d0	1.55±0.10
d1	1.00±0.05
E	1.75±0.10
F	3.50±0.10
K0	1.10±0.10
P	4.00±0.10
P0	4.00±0.10
P1	2.00±0.10
W	8.00±0.30
T	0.20 ±0.05

**Packaging Reel**



SYMBOL	MILLIMETER
A	177.8±0.2
B	3.1
C	13.50
D	9.6±0.3
E	75±0.2
F	12.3±0.3
T1	1.0±0.2
Quantity	3000PCS

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Specifications are subject to change without notice.

Please refer to <http://www.born-tw.com> for current information.

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